What is claimed is:

1. A method for manufacturing a mounting substrate, comprising:

forming a plurality of electrodes which are electrically connected via plating wires on a mounting substrate;

energizing the electrodes via the plating wires to coat the electrodes with plated films by electroplating; and

electrically separating the individual electrodes from each other by cutting off the plating wires.

2. A method for manufacturing a mounting substrate, comprising:

providing electrodes which are arranged in plurality of rows to surround a circuit element disposed in the vicinity of a center part of a mounting substrate and connecting the adjacent electrodes with each other by use of plating wires;

energizing the electrodes to each other via the plating wires to coat the electrodes with plated films by electroplating; and

electrically separating the individual electrodes from each other by cutting off the plating wires.

3. The method of claim 1 or 2, wherein

front face electrodes functioning as bonding pads are formed on a surface of the mounting substrate,

back face electrodes are formed on a back of the mounting substrate, which are connected to the front face electrodes and function as external electrodes, and the back face electrodes are connected to each other by the plating wires.

4. The method of claim 1 or 2, wherein

a number of the electrodes are formed in a matrix form and the electrodes are

coated with the plated films in a state where all the electrodes are electrically connected to each other by the plating wires.

5. The method of claim 1 or 2, wherein the plating wires are cut off by dicing.

6. A method for manufacturing a circuit device, comprising:

forming a plurality of electrodes on a mounting substrate, the plurality of electrodes being electrically connected to each other by use of plating wires;

energizing the electrodes via the plating wires to coat the electrodes with plated films by electroplating;

electrically separating the individual electrodes from each other by cutting off the plating wires;

fixing a circuit element on the mounting substrate and electrically connecting the electrodes with the circuit element; and

forming a sealing resin to cover the circuit element.

7. A method for manufacturing a circuit device, comprising:

providing electrodes which are arranged in plurality of rows to surround a circuit element disposed in the vicinity of a center part of a mounting substrate and connecting the adjacent electrodes to each other by use of plating wires;

energizing the electrodes via the plating wires to coat the electrodes with plated films by electroplating;

electrically separating the individual electrodes from each other by cutting off the plating wires;

fixing a circuit element on the mounting substrate and electrically connecting the electrodes to the circuit element; and

forming a sealing resin to cover the circuit element.

8. The method of claim 6 or 7, wherein

front face electrodes functioning as bonding pads are formed on a surface of the mounting substrate,

back face electrodes are formed on a back of the mounting substrate, which are connected to the front face electrodes and function as external electrodes, and the back face electrodes are connected to each other by the plating wires.

9. The method of claim 6 or 7, wherein

a number of the electrodes are formed in a matrix form and the electrodes are coated with the plated films in a state where all the electrodes are electrically connected to each other by the plating wires.

10. The method of claims 6 and 7, wherein the plating wires are cut off by dicing.